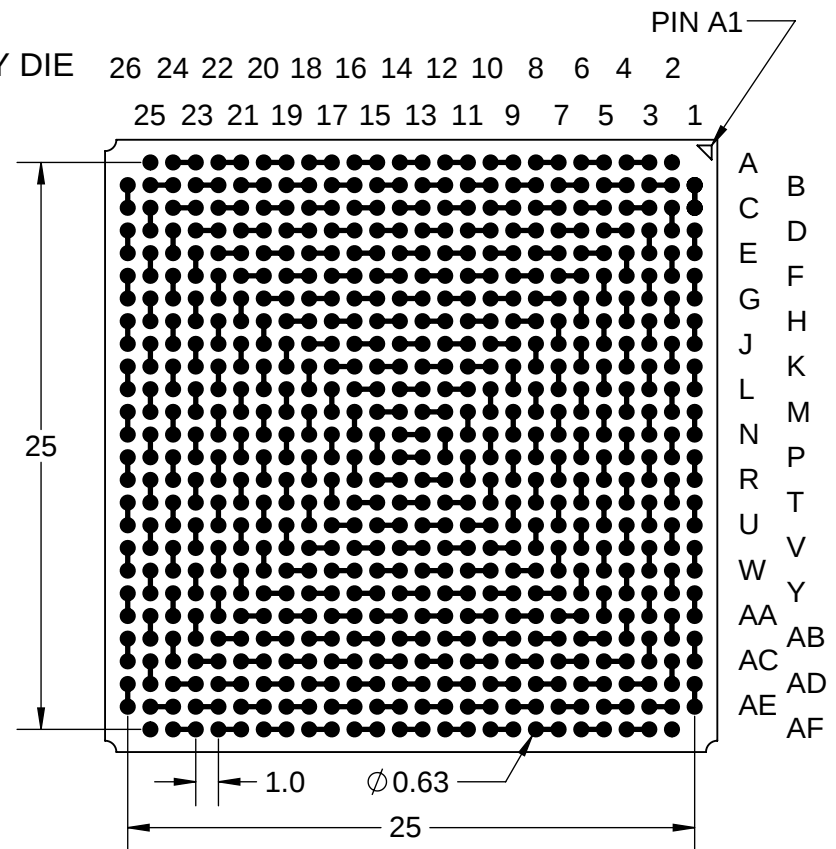


BALL VIEW



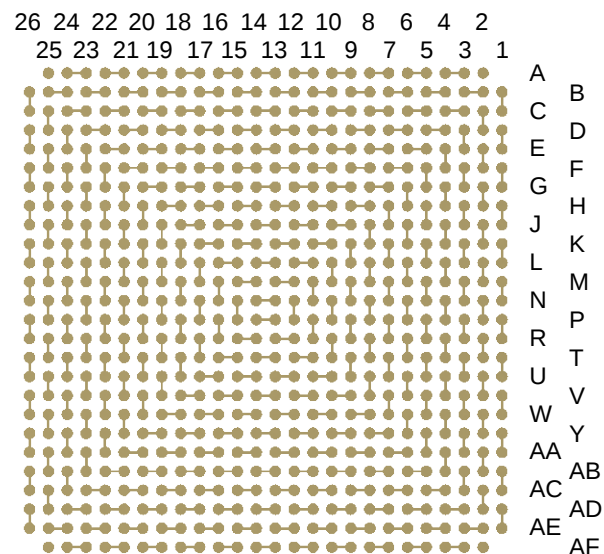
Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.63mm (25 MIL).
- 4) SOLDER MASK DEFINED PAD OPENING: 0.45mm (17.7 MIL).
- 5) PAD Cu DIAMETER: 0.60mm (23.6 MIL).
- 6) SUBSTRATE MATERIAL: BT.
- 7) DUMMY DIE IS OPTIONAL.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR SOLDERING TO PC BOARD.

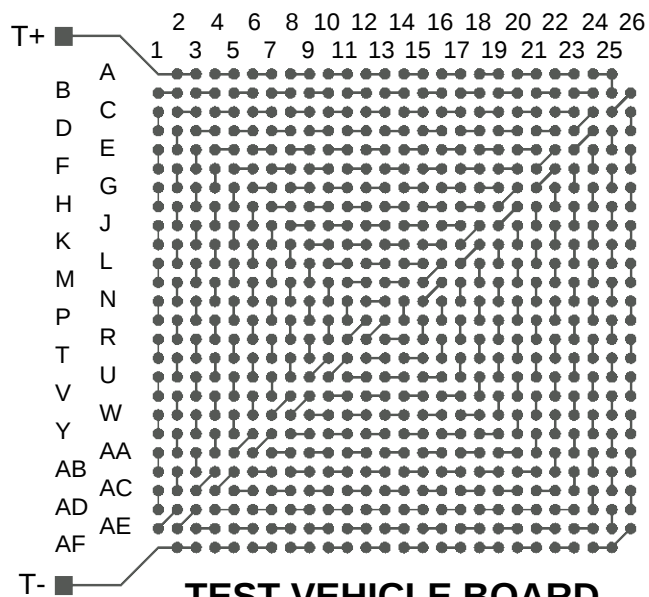
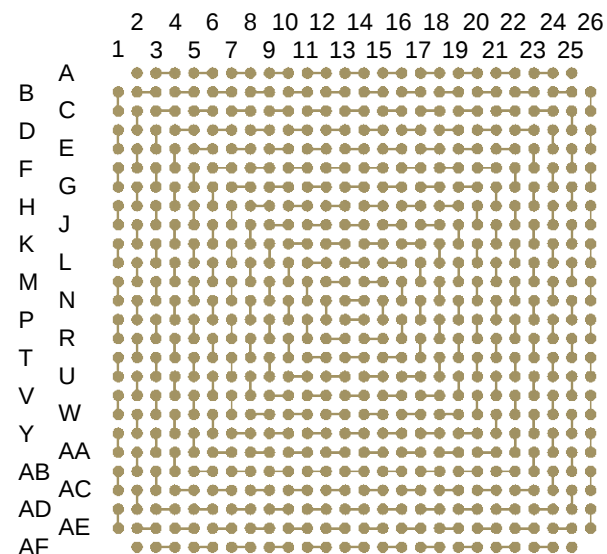
APPROVALS	DATE				
DRAWN T.Au	3/21/2019				
ENG M. Hart	3/21/2019	TITLE BGA672T1.0C-DC261BD DAISY CHAIN DUMMY			
MFG					
QA		SCALE 3:1	SIZE A	DRAWING NO. 512614	REV A
CUST					
REVISED		DO NOT SCALE DRAWING			SHEET 1 OF 3

PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-Free	RoHS	Si DIE
BGA672T1.0C-DC261BD	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
BGA672T1.0-DC261BD	Sn63/Pb37	NO	NO	YES

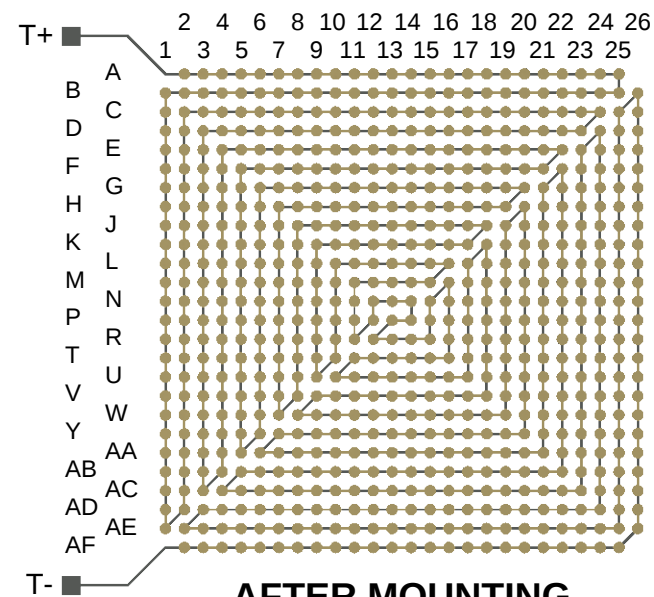
BALL VIEW



BOTTOM SIDE (TOP X-RAY VIEW)



TEST VEHICLE BOARD



AFTER MOUNTING

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER: 0.60mm (23.6 MIL).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH: 0.15mm (6 MIL).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING: 0.45mm (17.7 MIL).

TopLine®

TITLE BGA672T1.0C-DC261BD
DAISY CHAIN DUMMY

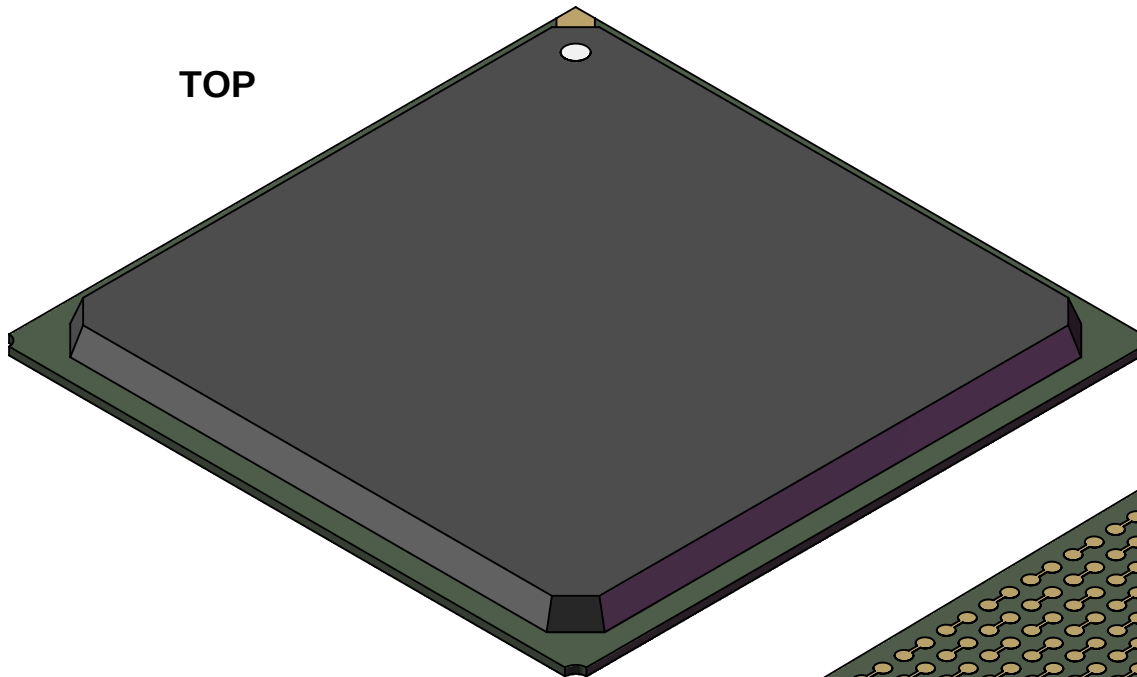
SCALE 2.5:1	SIZE A	DRAWING NO. 512614	REV A
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DO NOT SCALE DRAWING

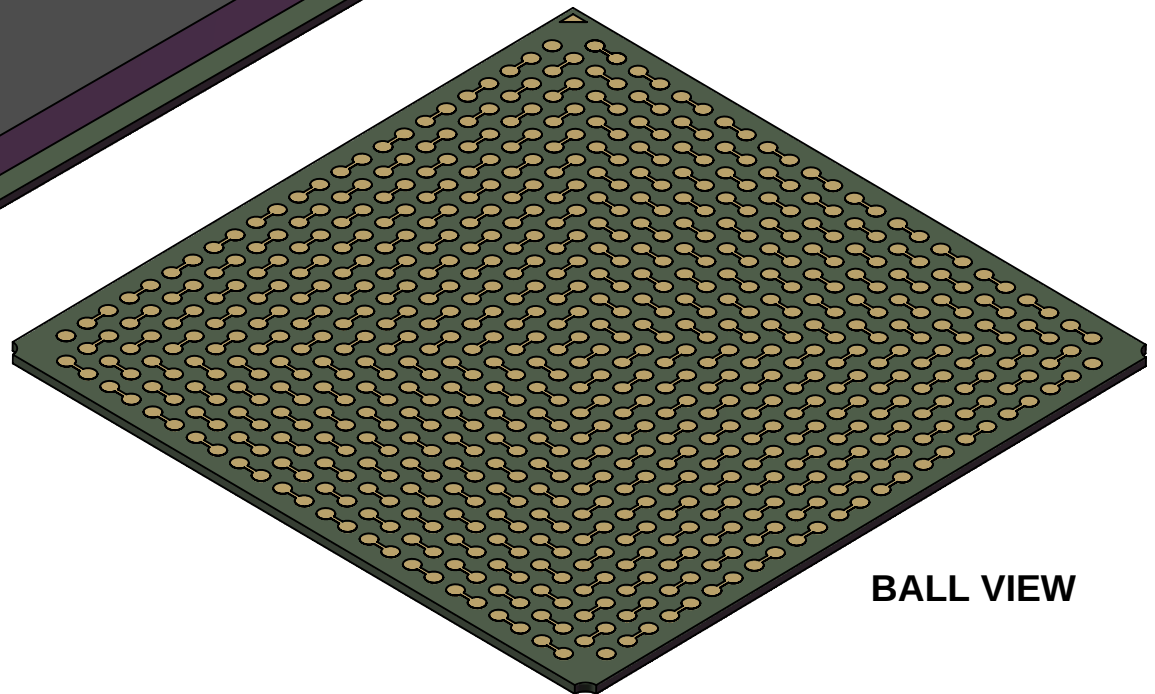
SHEET 2 OF 3

MODEL

TOP



BALL VIEW



TopLine[®]

TITLE BGA672T1.0C-DC261BD
DAISY CHAIN DUMMY

SCALE 4:1	SIZE A	DRAWING NO. 512614	REV A
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DO NOT SCALE DRAWING

SHEET 3 OF 3